

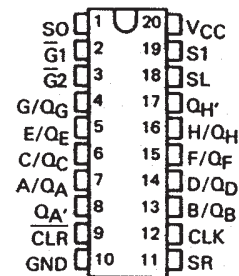
SN54LS299, SN54S299, SN74LS299, SN74S299 8-BIT UNIVERSAL SHIFT/STORAGE REGISTERS

SDLS156 – MARCH 1974 – REVISED MARCH 1988

- Multiplexed Inputs/Outputs Provide Improved Bit Density
- Four Modes of Operations:
Hold (Store) Shift Left
Shift Right Load Data
- Operates with Outputs Enabled or at High Z
- 3-State Outputs Drive Bus Lines Directly
- Can Be Cascaded for N-Bit Word Lengths
- SN54LS323 and SN74LS323 Are Similar But Have Synchronous Clear

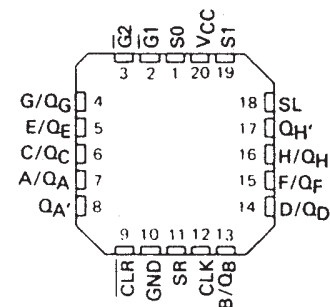
SN54LS299, SN54S299 . . . J OR W PACKAGE
SN74LS299, SN74S299 . . . DW OR N PACKAGE

(TOP VIEW)



SN54LS299, SN54S299 . . . FK PACKAGE

(TOP VIEW)



- Applications:
Stacked or Push-Down Registers
Buffer Storage, and Accumulator Registers

TYPE	GUARANTEED SHIFT (CLOCK) FREQUENCY	TYPICAL POWER DISSIPATION
'LS299	25 MHz	175 mW
'S299	50 MHz	700 mW

description

These Schottky TTL eight-bit universal registers feature multiplexed inputs/outputs to achieve full eight-bit data handling in a single 20-pin package. Two function-select inputs and two output-control inputs can be used to choose the modes of operation listed in the function table.

Synchronous parallel loading is accomplished by taking both function-select lines, S0 and S1, high. This places the three-state outputs in a high-impedance state, which permits data that is applied on the input/output lines to be clocked into the register. Reading out of the register can be accomplished while the outputs are enabled in any mode. A direct overriding input is provided to clear the register whether the outputs are enabled or off.

FUNCTION TABLE

MODE	INPUTS						INPUTS/OUTPUTS								OUTPUTS			
	CLR	FUNCTION SELECT		OUTPUT CONTROL		CLK	SERIAL		A/Q _A	B/Q _B	C/Q _C	D/Q _D	E/Q _E	F/Q _F	G/Q _G	H/Q _H	Q _A '	Q _H '
		S ₁	S ₀	G ₁ [†]	G ₂ [†]		SL	SR										
Clear	L	X	L	L	L	X	X	X	L	L	L	L	L	L	L	L	L	L
	L	L	X	L	L	X	X	X	L	L	L	L	L	L	L	L	L	L
	L	H	H	X	X	X	X	X	X	X	X	X	X	X	X	X	L	L
Hold	H	L	L	L	[*] L	X	X	X	Q _{A0}	Q _{B0}	Q _{C0}	Q _{D0}	Q _{E0}	Q _{F0}	Q _{G0}	Q _{H0}	Q _{A0}	Q _{H0}
	H	X	X	L	L	L	X	X	Q _{A0}	Q _{B0}	Q _{C0}	Q _{D0}	Q _{E0}	Q _{F0}	Q _{G0}	Q _{H0}	Q _{A0}	Q _{H0}
Shift Right	H	L	H	L	L	†	X	H	H	Q _{An}	Q _{Bn}	Q _{Cn}	Q _{Dn}	Q _{En}	Q _{Fn}	Q _{Gn}	H	Q _{Gn}
	H	L	H	L	L	†	X	L	L	Q _{An}	Q _{Bn}	Q _{Cn}	Q _{Dn}	Q _{En}	Q _{Fn}	Q _{Gn}	L	Q _{Gn}
Shift Left	H	H	L	L	L	†	H	X	Q _{Bn}	Q _{Cn}	Q _{Dn}	Q _{En}	Q _{Fn}	Q _{Gn}	Q _{Hn}	H	Q _{Bn}	H
	H	H	L	L	L	†	L	X	Q _{Bn}	Q _{Cn}	Q _{Dn}	Q _{En}	Q _{Fn}	Q _{Gn}	Q _{Hn}	L	Q _{Bn}	L
Load	H	H	H	X	X	†	X	X	a	b	c	d	e	f	g	h	a	h

† When one or both output controls are high the eight input/output terminals are disabled to the high-impedance state; however, sequential operation or clearing of the register is not affected.

a . . . h = the level of the steady-state input at inputs A through H, respectively. These data are loaded into the flip-flops while the flip-flop outputs are isolated from the input/output terminals.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS
INSTRUMENTS**

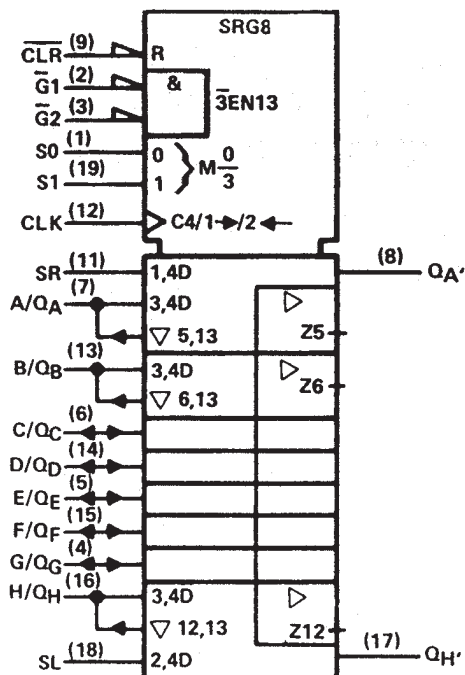
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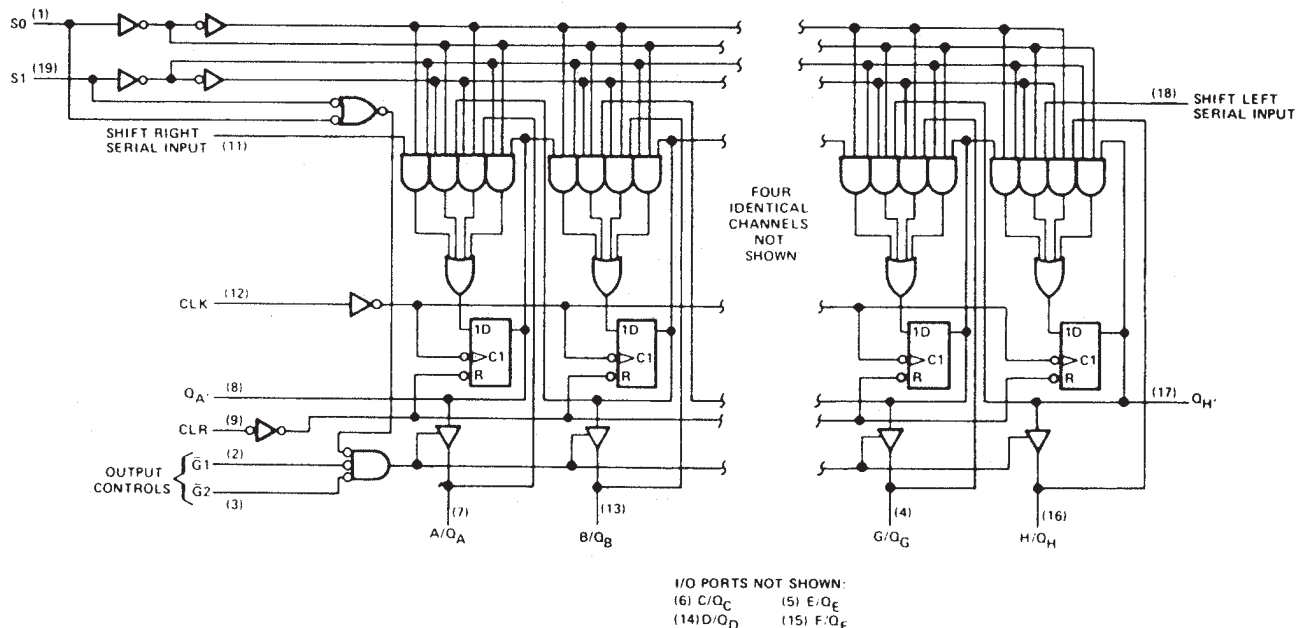
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logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for DW, J, N, and W packages.

logic diagram (positive logic)

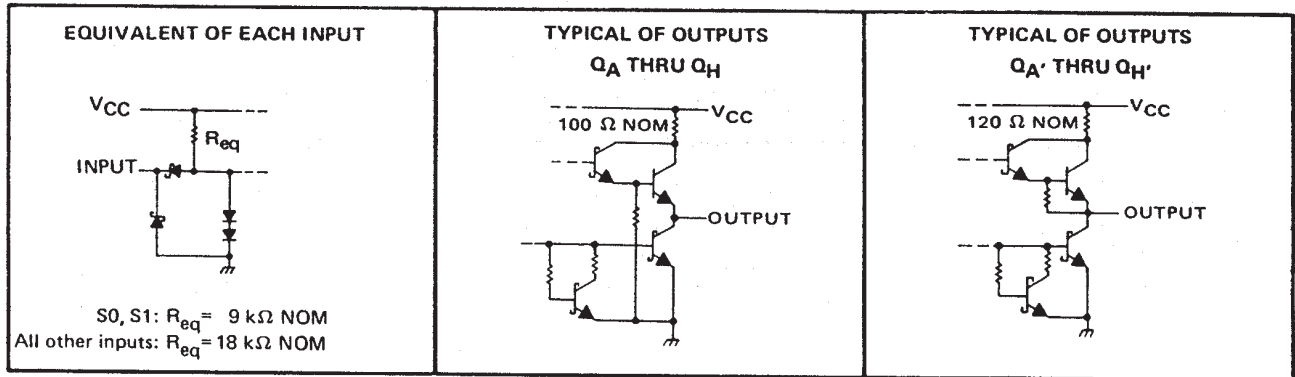


Pin numbers shown are for DW, J, N, and W packages.

SN54LS299, SN54S299, SN74LS299, SN74S299 8-BIT UNIVERSAL SHIFT/STORAGE REGISTERS

SDLS156 – MARCH 1974 – REVISED MARCH 1988

schematics of inputs and outputs



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1)	7 V
Input voltage	7 V
Off-state output voltage	5.5 V
Operating free-air temperature range: SN54LS299	-55°C to 125°C
SN74LS299	0°C to 70°C
Storage temperature	-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

		SN54LS299			SN74LS299			UNIT	
		MIN	NOM	MAX	MIN	NOM	MAX		
Supply voltage, V _{CC}		4.5	5	5.5	4.75	5	5.25	V	
High-level output current, I _{OH}	Q _A thru Q _H	-1			-2.6			mA	
	Q _A ' or Q _H '	-0.4			-0.4				
Low-level output current, I _{OL}	Q _A thru Q _H	12			24			mA	
	Q _A ' or Q _H '	4			8				
Clock frequency, f _{clock}		0			0			20	MHz
Width of clock pulse, t _w (clock)	Clock high	30			30			ns	
	Clock low	18			10				
Width of clear pulse, t _w (clear)	Clear low	25			20			ns	
Setup time, t _{su}	Select	35†			35†			ns	
	High-level data†	20†			20†				
	Low-level data†	20†			20†				
	Clear inactive-state	24†			20†				
Hold time, t _h	Select	10†			10†			ns	
	Data†	3†			0†				
Operating free-air temperature, T _A		-55			0			70	°C

† Data includes the two serial inputs and the eight input/output data lines.

SN54LS299, SN54S299, SN74LS299, SN74S299

8-BIT UNIVERSAL SHIFT/STORAGE REGISTERS

SDLS156 – MARCH 1974 – REVISED MARCH 1988

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS†	SN54LS299			SN74LS299			UNIT	
			MIN	TYP‡	MAX	MIN	TYP‡	MAX		
V _{IH}	High-level input voltage		2			2			V	
V _{IL}	Low-level input voltage		0.7			0.8			V	
V _{IK}	Input clamp voltage	V _{CC} = MIN, I _I = -18 mA	-1.5			-1.5			V	
V _{OH}	High-level output voltage	Q _A thru Q _H	V _{CC} = MIN, V _{IH} = 2 V,	2.4	3.2	2.4	3.1	V		
		Q _A ' or Q _H '	V _{IL} = V _{ILmax} , I _{OH} = MAX	2.5	3.4	2.7	3.4			
V _{OL}	Low-level output voltage	Q _A thru Q _H	V _{CC} = MIN, V _{IH} = 2 V, V _{IL} = V _{ILmax}	I _{OL} = 12 mA	0.25	0.4	0.25	0.4	V	
				I _{OL} = 24 mA			0.35	0.5		
		Q _A ' or Q _H '		I _{OL} = 4 mA	0.25	0.4	0.25	0.4		
				I _{OL} = 8 mA			0.35	0.5		
I _{OZH}	Off-state output current, high-level voltage applied	Q _A thru Q _H	V _{CC} = MAX, V _{IH} = 2 V, V _O = 2.7 V	40			40		μA	
I _{OZL}	Off-state output current, low-level voltage applied	Q _A thru Q _H	V _{CC} = MAX, V _{IH} = 2 V, V _O = 0.4 V	-400			-400		μA	
I _I	Input current at maximum input voltage	S0, S1	V _{CC} = MAX	V _I = 7 V	200			200		μA
		A thru H		V _I = 5.5 V	100			100		
		Any other		V _I = 7 V	100			100		
I _{IH}	High-level input current	A thru H, S0, S1	V _{CC} = MAX, V _I = 2.7 V	40			40		μA	
		Any other		20			20			
I _{IL}	Low-level input current	S0, S1	V _{CC} = MAX, V _I = 0.4 V	-0.8			-0.8		mA	
		Any other		-0.4			-0.4			
I _{OS}	Short-circuit output current§	Q _A thru Q _H	V _{CC} = MAX	-30	-130	-30	-130	mA		
		Q _A ' or Q _H '		-20	-100	-20	-100			
I _{CC}	Supply current	V _{CC} = MAX	33 53			33 53			mA	

†For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡All typical values are at $V_{CC} = 5 \text{ V}, T_A = 25^\circ\text{C}$.

§Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second.

switching characteristics, $V_{CC} = 5 \text{ V}, T_A = 25^\circ\text{C}$

PARAMETER¶	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
f_{max}			See Note 2	20	35		MHz
t_{PLH}	CLK	Q_A' or Q_H'	$R_L = 2 \text{ k}\Omega, C_L = 15 \text{ pF}$		22	33	ns
t_{PHL}		Q_A' or Q_H'			26	39	
t_{PHL}	$\overline{\text{CLR}}$	Q_A' or Q_H'			27	40	ns
t_{PLH}	CLK	Q_A thru Q_H	$R_L = 665 \Omega, C_L = 45 \text{ pF}$		17	25	ns
t_{PHL}		Q_A thru Q_H			26	39	
t_{PHL}	$\overline{\text{CLR}}$	Q_A thru Q_H			26	40	ns
t_{PZH}	$\overline{G1}, \overline{G2}$	Q_A thru Q_H			13	21	ns
t_{PZL}		Q_A thru Q_H			19	30	
t_{PHZ}	$\overline{G1}, \overline{G2}$	Q_A thru Q_H	$R_L = 665 \Omega, C_L = 5 \text{ pF}$		10	20	ns
t_{PLZ}		Q_A thru Q_H			10	15	

¶ f_{max} = maximum clock frequency

t_{PLH} = propagation delay time, low-to-high-level output

t_{PHL} = propagation delay time, high-to-low-level output

t_{PZH} = output enable time to high level

t_{PZL} = output enable time to low level

t_{PHZ} = output disable time from high level

t_{PLZ} = output disable time from low level

NOTE 2: For testing f_{max} , all outputs are loaded simultaneously, each with C_L and R_L as specified for the propagation times. Load circuits and voltage waveforms are shown in Section 1.

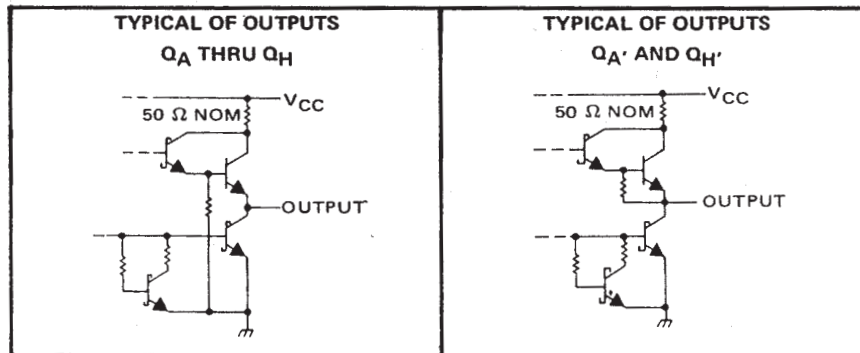
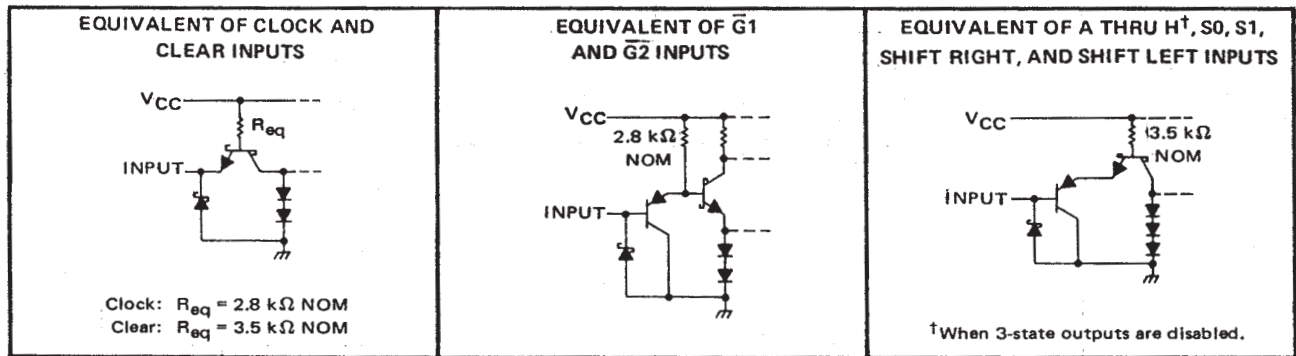


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SN54LS299, SN54S299, SN74LS299, SN74S299 8-BIT UNIVERSAL SHIFT/STORAGE REGISTERS

SDLS156 – MARCH 1974 – REVISED MARCH 1988

schematics of inputs and outputs



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1)	7 V
Input voltage	5.5 V
Off-state output voltage	5.5 V
Operating free-air temperature range: SN54S299 (See Note 1)	–55 °C to 125 °C
SN74S299	0 °C to 70 °C
Storage temperature range	–65 °C to 150 °C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

		SN54S299			SN74S299			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V_{CC}		4.5	5	5.5	4.75	5	5.25	V
High-level output current, I_{OH}	Q_A thru Q_H	—2			—6.5			mA
	Q_A' or Q_H'	—0.5			—0.5			
Low-level output current, I_{OL}	Q_A thru Q_H	20			20			mA
	Q_A' or Q_H'	6			6			
Clock frequency, f_{clock}		0		50	0		50	MHz
Width of clock pulse, $t_w(\text{clock})$	Clock high	10			10			ns
	Clock low	10			10			
Width of clear pulse, $t_w(\text{clear})$		10			10			ns
Setup time, t_{su}	Select	15†			15†			ns
	High-level data†	7†			7†			
	Low-level data†	5†			5†			
	Clear inactive-state	10†			10†			
Hold time, t_h	Select	5†			5†			ns
	Data†	5†			5†			
Operating free-air temperature, T_A		—55		125	0		70	°C

[†] Data includes the two serial inputs and the eight input/output data lines.



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SN54LS299, SN54S299, SN74LS299, SN74S299 8-BIT UNIVERSAL SHIFT/STORAGE REGISTERS

SDLS156 – MARCH 1974 – REVISED MARCH 1988

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS†	MIN	TYP‡	MAX	UNIT
V_{IH}	High-level input voltage		2			V
V_{IL}	Low-level input voltage				0.8	V
V_{IK}	Input clamp voltage	$V_{CC} = \text{MIN}, I_I = -18 \text{ mA}$			-1.2	V
V_{OH}	High-level output voltage	Q_A thru Q_H	$V_{CC} = \text{MIN}, V_{IH} = 2 \text{ V},$	2.4	3.2	V
		Q_A' or Q_H'	$V_{IL} = 0.8 \text{ V}, I_{OH} = \text{MAX}$	2.7	3.4	
V_{OL}	Low-level output voltage	$V_{CC} = \text{MIN}, V_{IH} = 2 \text{ V},$ $V_{IL} = 0.8 \text{ V}, I_{OL} = \text{MAX}$			0.5	V
I_{OZH}	Off-state output current, high-level voltage applied	Q_A thru Q_H	$V_{CC} = \text{MAX}, V_{IH} = 2 \text{ V},$ $V_O = 2.4 \text{ V}$		100	μA
I_{OZL}	Off-state output current, low-level voltage applied	Q_A thru Q_H	$V_{CC} = \text{MAX}, V_{IH} = 2 \text{ V},$ $V_O = 0.5 \text{ V}$		-250	μA
I_I	Input current at maximum input voltage	$V_{CC} = \text{MAX}, V_I = 5.5 \text{ V}$		1		mA
I_{IH}	High-level input current	A thru H, S0, S1	$V_{CC} = \text{MAX}, V_I = 2.7 \text{ V}$	100		μA
		Any other		50		
I_{IL}	Low-level input current	CLK or $\overline{\text{CLR}}$	$V_{CC} = \text{MAX}, V_I = 0.5 \text{ V}$	-2		mA
		S0, S1		-500		μA
		Any other		-250		μA
I_{OS}	Short-circuit output current§	Q_A thru Q_H	$V_{CC} = \text{MAX}$	-40	-100	mA
		Q_A' or Q_H'		-20	-100	
I_{CC}	Supply current	$V_{CC} = \text{MAX}$		140	225	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at $V_{CC} = 5 \text{ V}, T_A = 25^\circ\text{C}$.

§ Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second.

switching characteristics, $V_{CC} = 5 \text{ V}, T_A = 25^\circ\text{C}$

PARAMETER¶	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
f _{max}			See Note 2	50	70		MHz
t _{PLH}	CLK	Q _A ' or Q _H '	R _L = 1 kΩ, C _L = 15 pF		12	20	ns
t _{PHL}					13	20	
t _{PHL}	CLR	Q _A ' or Q _H '			14	21	ns
t _{PLH}	CLK	Q _A thru Q _H	R _L = 280 Ω, C _L = 45 pF		15	21	ns
t _{PHL}					15	21	
t _{PHL}	CLR	Q _A thru Q _H			16	24	ns
t _{PZH}	G1, G2	Q _A thru Q _H			10	18	ns
t _{PZL}					12	18	
t _{PHZ}	G1, G2	Q _A thru Q _H	R _L = 280 Ω, C _L = 5 pF		7	12	ns
t _{PLZ}							

¶ f_{max} = maximum clock frequency

t_{PLH} = Propagation delay time, low-to-high-level output

t_{PHL} = Propagation delay time, high-to-low-level output

t_{PZH} = output enable time to high level

t_{PZL} = output enable time to low level

t_{PHZ} = output disable time from high level

t_{PLZ} = output disable time from low level

NOTE 2: For testing f_{max} , all outputs are loaded simultaneously, each with C_L and R_L as specified for the propagation times.

Load circuits and voltage waveforms are shown in Section 1.



PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
78024012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	78024012A SNJ54LS 299FK	Samples
7802401RA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	7802401RA SNJ54LS299J	Samples
7802401RA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	7802401RA SNJ54LS299J	Samples
7802401SA	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	7802401SA SNJ54LS299W	Samples
7802401SA	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	7802401SA SNJ54LS299W	Samples
SN54LS299J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS299J	Samples
SN54LS299J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS299J	Samples
SN54S299J	OBSOLETE	CDIP	J	20		TBD	Call TI	Call TI	-55 to 125		
SN54S299J	OBSOLETE	CDIP	J	20		TBD	Call TI	Call TI	-55 to 125		
SN74LS299DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS299	Samples
SN74LS299DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS299	Samples
SN74LS299DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS299	Samples
SN74LS299DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS299	Samples
SN74LS299DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS299	Samples
SN74LS299DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS299	Samples
SN74LS299N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS299N	Samples
SN74LS299N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS299N	Samples
SN74LS299NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS299N	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LS299NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS299N	Samples
SN74S299DW	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI	0 to 70		
SN74S299DW	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI	0 to 70		
SN74S299DWR	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI	0 to 70		
SN74S299DWR	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI	0 to 70		
SN74S299N	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI	0 to 70		
SN74S299N	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI	0 to 70		
SN74S299N3	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI	0 to 70		
SN74S299N3	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI	0 to 70		
SNJ54LS299FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	78024012A SNJ54LS 299FK	Samples
SNJ54LS299FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	78024012A SNJ54LS 299FK	Samples
SNJ54LS299J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	7802401RA SNJ54LS299J	Samples
SNJ54LS299J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	7802401RA SNJ54LS299J	Samples
SNJ54LS299W	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	7802401SA SNJ54LS299W	Samples
SNJ54LS299W	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	7802401SA SNJ54LS299W	Samples
SNJ54S299FK	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI	-55 to 125		
SNJ54S299FK	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI	-55 to 125		
SNJ54S299J	OBSOLETE	CDIP	J	20		TBD	Call TI	Call TI	-55 to 125		
SNJ54S299J	OBSOLETE	CDIP	J	20		TBD	Call TI	Call TI	-55 to 125		
SNJ54S299W	OBSOLETE	CFP	W	20		TBD	Call TI	Call TI	-55 to 125		
SNJ54S299W	OBSOLETE	CFP	W	20		TBD	Call TI	Call TI	-55 to 125		

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "--" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

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OTHER QUALIFIED VERSIONS OF SN54LS299, SN54S299, SN74LS299, SN74S299 :

● Catalog: [SN74LS299](#), [SN74S299](#)

● Military: [SN54LS299](#), [SN54S299](#)

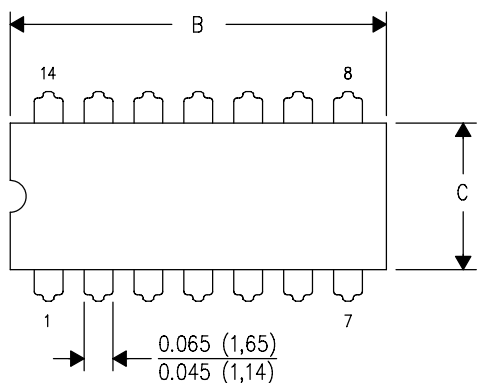
NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

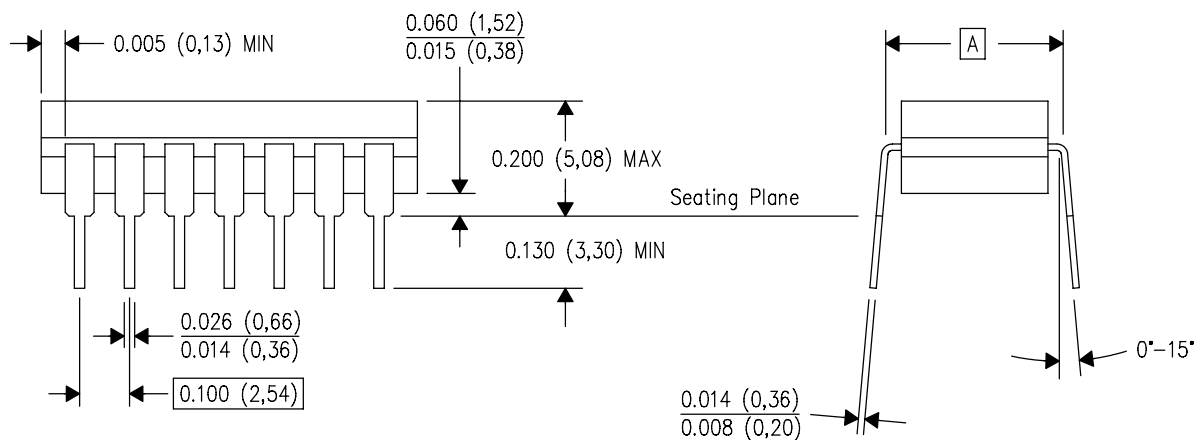
J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

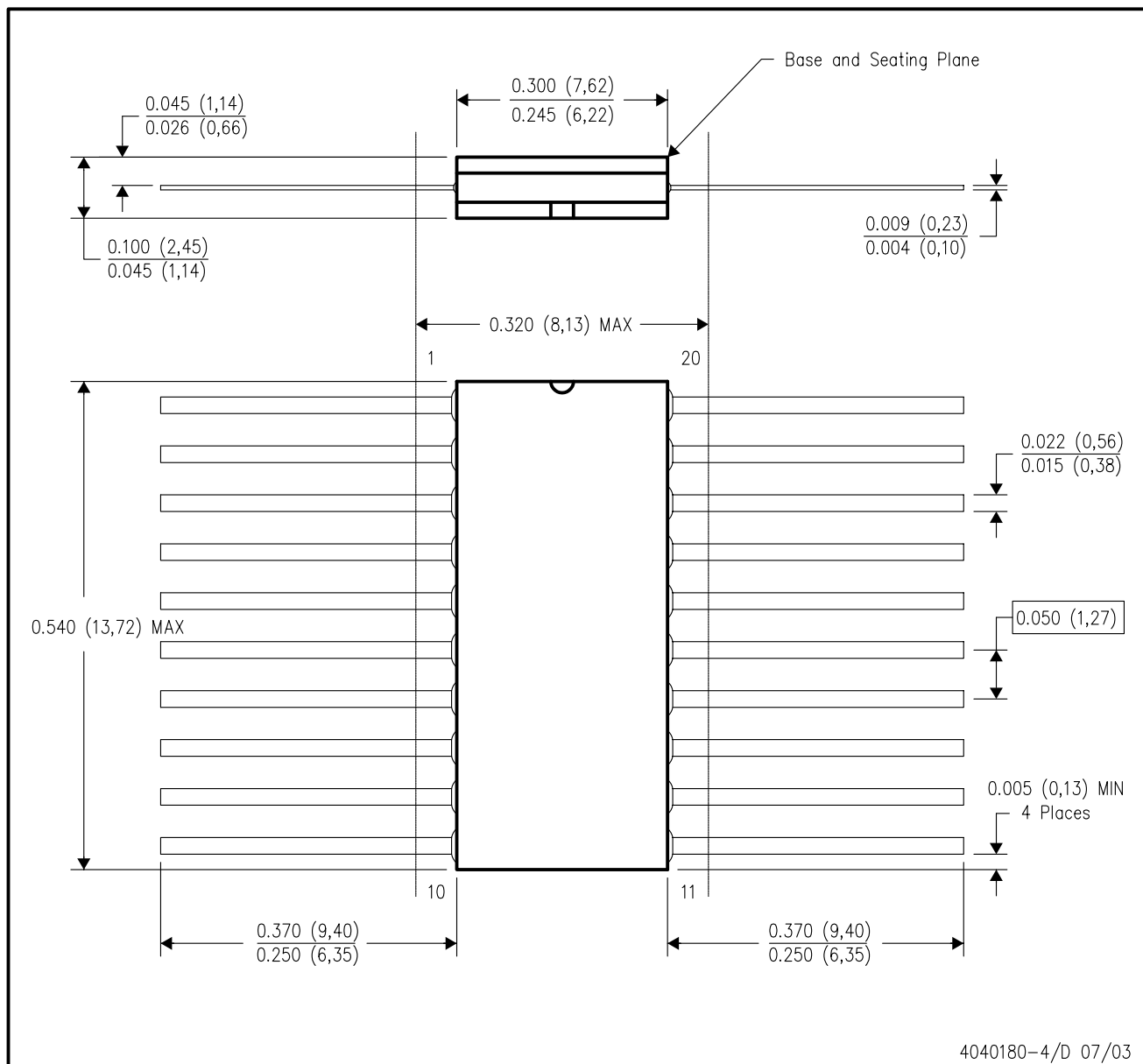


4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK

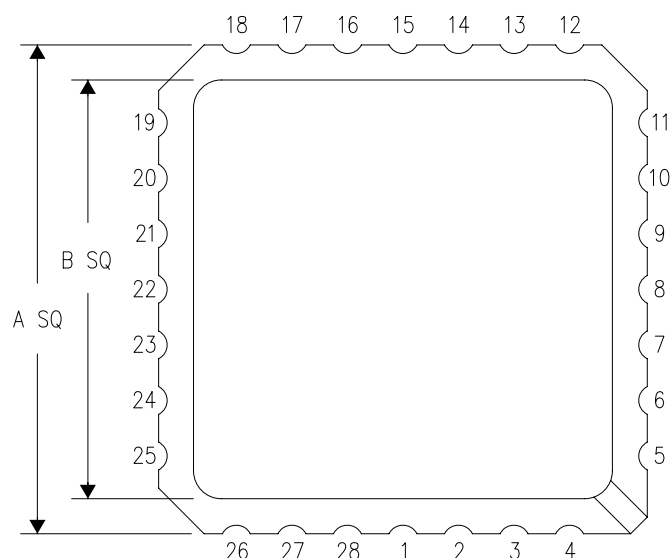


- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only.
 - Falls within Mil-Std 1835 GDFP2-F20

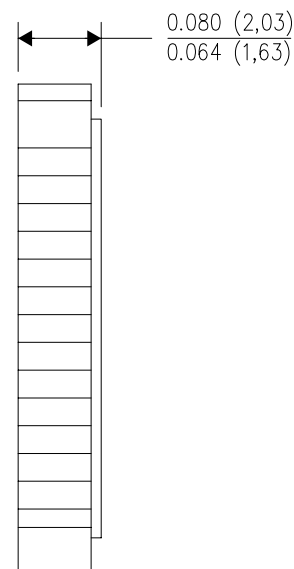
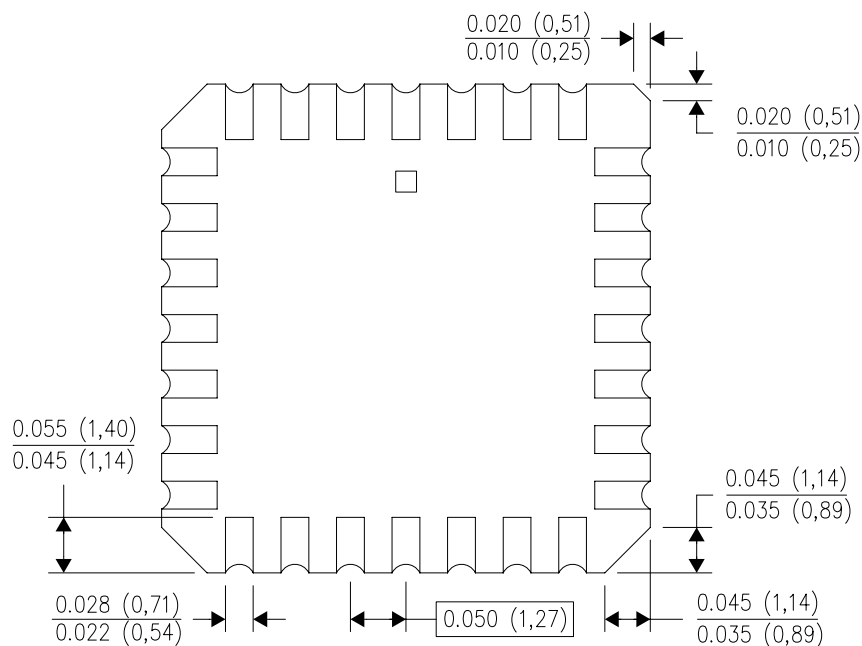
FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



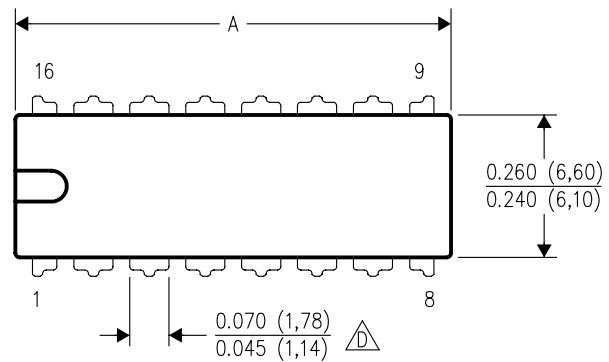
4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a metal lid.
 - Falls within JEDEC MS-004

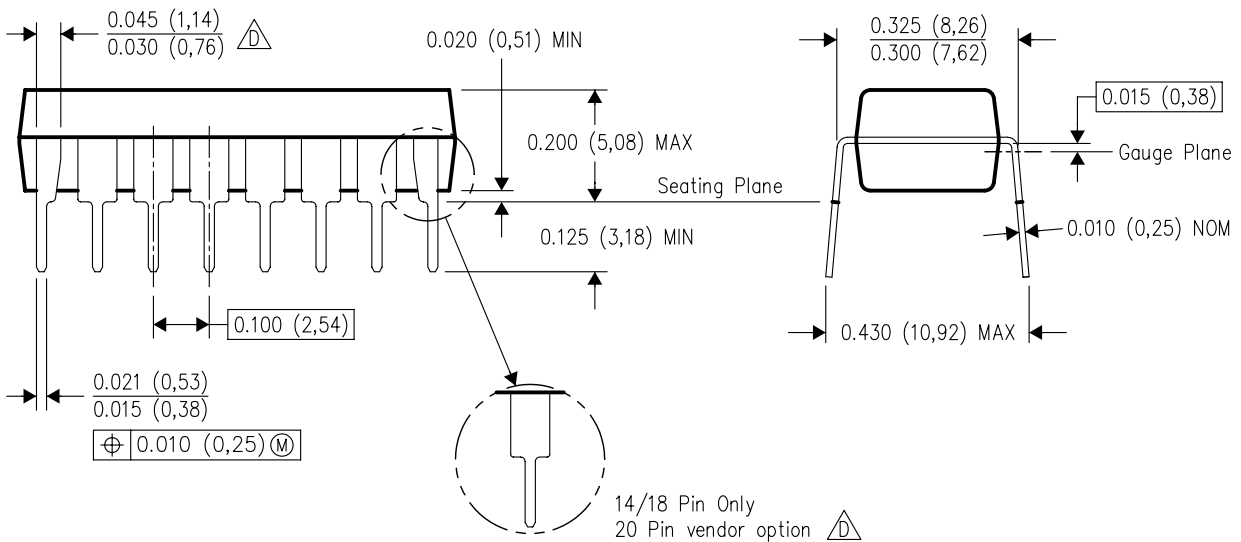
N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



PINS **	14	16	18	20
DIM				
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



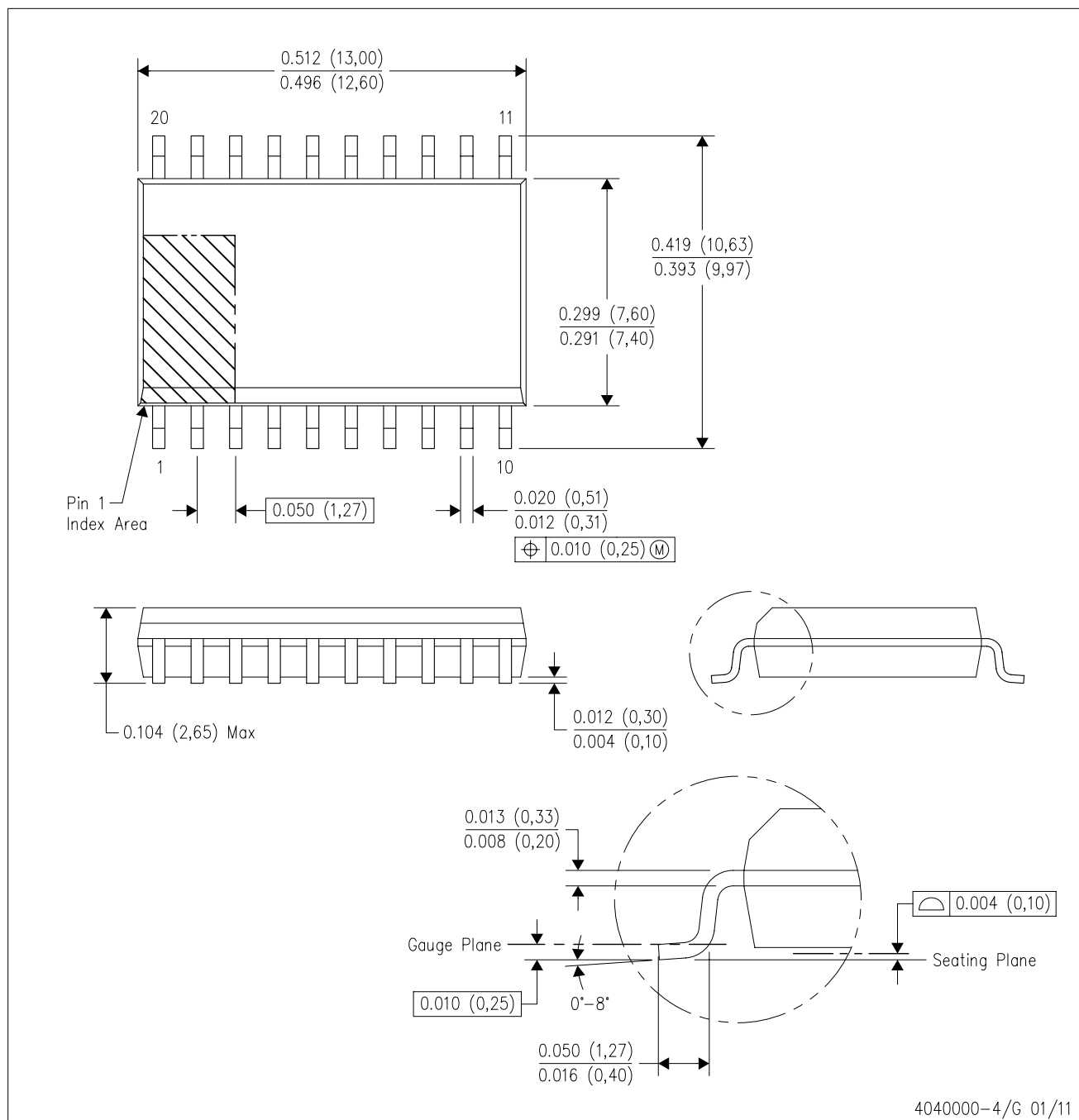
14/18 Pin Only
20 Pin vendor option

4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

DW (R-PDSO-G20)

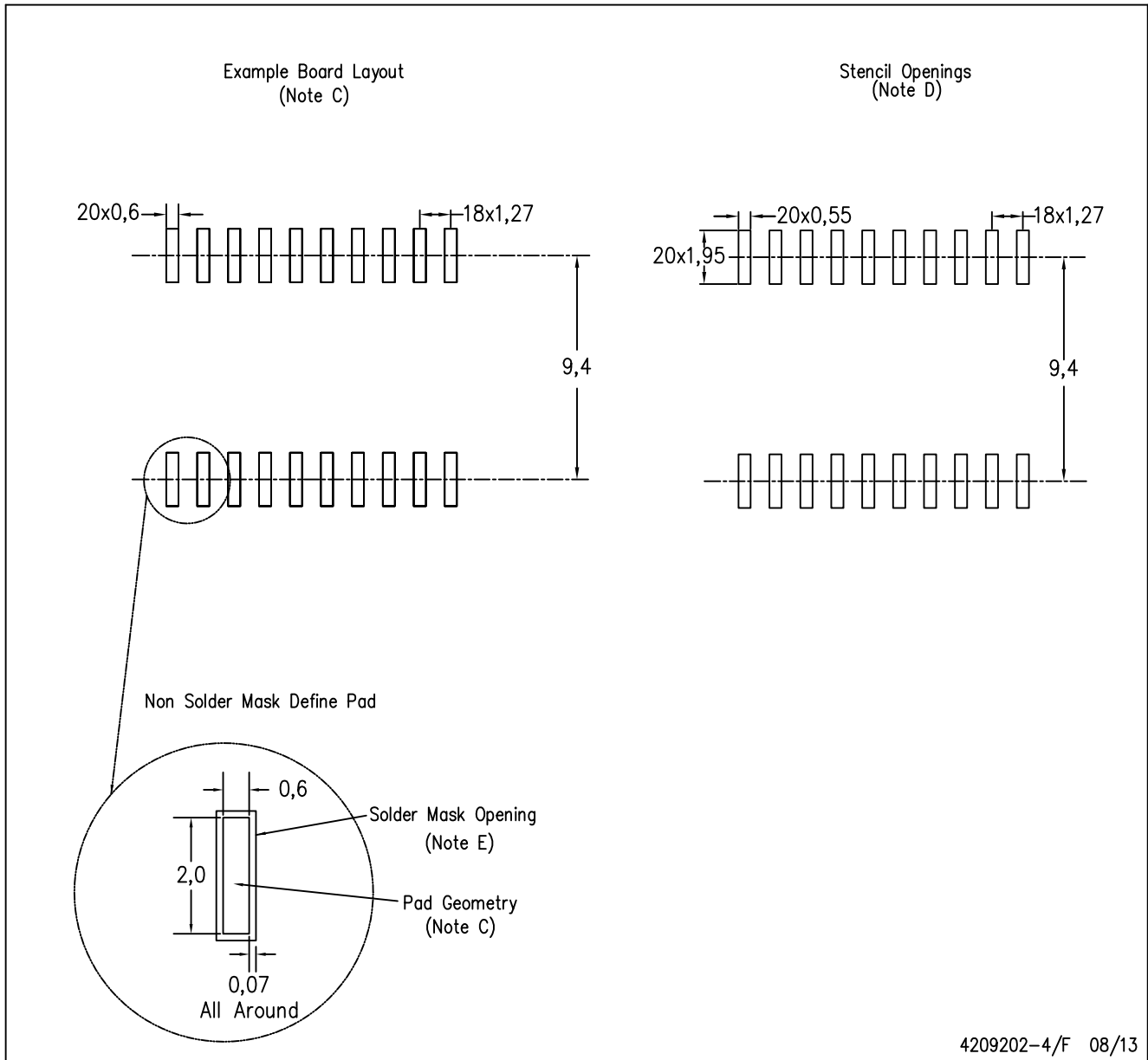
PLASTIC SMALL OUTLINE



- NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
D. Falls within JEDEC MS-013 variation AC.

DW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Refer to IPC7351 for alternate board design.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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